

06-09-2004



Attorney Docket No. A8316/T52800

FORM PTO-1595 (Rev. 6-93)

102761829

et

U.S. Department of Commerce Patent and Trademark Office

To the Honorable Commissioner for Patents. Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

Jeong Soo Byun	<u>Execution Date</u>
Zheng Yuan	<u>5/26/04</u>
Shankar Venkataraman	<u>5/24/04</u>
M. Ziaul Karim	<u>5/24/04</u>
Thanh N. Pham	<u>5/28/04</u>
Ellie Y. Yieh	<u>5/24/04</u>

2. Name and address of receiving party(ies)

Name: Applied Materials, Inc.

Internal Address: Legal Affairs Department

Street Address: P.O. Box 450A

City: Santa Clara State: CA ZIP: 95052

16834 U.S. PTO
10/857829
060104

Additional name(s) of conveying parties attached? Yes No.

Additional names and addresses attached? Yes No

3. Nature of conveyance: **6-1-04**

Assignment Merger

Security Agreement Change of Name

Other:

Execution Date: SEE ABOVE

4. Application Number(s) or Patent Numbers.

If this document is being filed together with a new application, the execution date of the application is: June 1, 2004

A. Patent Application No(s): **10857829** B. Patent No(s):

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Patent Counsel
APPLIED MATERIALS, INC.
Legal Affairs Department
P.O. Box 450A, M/S 2061
Santa Clara, California 95052

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

Enclosed Charge Fees to Deposit Account

Charge any additional fees associated with this paper or during the pendency of this application, or credit any overpayment, to deposit account.

8. Deposit account number: 50-1074

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true of copy of the original document.

Robert W. Mulcahy
Name of Person Signing

Signature

June 1, 2004
Date

Atty Reg. No. 25,436 Total number of pages including cover sheet, attachments and document: 5

10. Change Correspondence Address to that of Part 5? Yes No

OMB No. 0651-0011 (exp. 4/94)

Mail documents to be recorded with required cover to: **06/08/2004 LHMULLER 00000202 501074 10857829**

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MS Assignment Recordation Services
Director of the U.S. Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses
of Inventors:

1)	Jeong Soo Byun 20975 Valley Green Drive, #257 Cupertino, CA 95014 United States	2)	Zheng Yuan 42024 Benbow Drive Fremont, CA 94539 United States
3)	Shankar Venkataraman 3444 Notre Dame Drive Santa Clara, CA 95051 United States	4)	M. Ziaul Karim 2820 McAnn Court San Jose, CA 95121 United States
5)	Thanh N. Pham 3794 Meadowlands Lane San Jose, CA 95135 United States	6)	Ellie Y. Yieh 5888 Pistola Way San Jose, CA 95138 United States

(hereinafter referred to as Assignors), have invented a certain invention entitled:

GAP FILLING WITH A COMPOSITE LAYER

for which application for Letters Patent in the United States was filed on , under Application No. Unassigned, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	<u>5/26/04</u>	, 2004	<u>J. S. Pyun</u> Jeong Soo Byun
2)	<u>5/24/04</u>	, 2004	<u>Zheng Yuan</u> Zheng Yuan
3)	<u>5/21/04</u>	, 2004	<u>Shankar Venkataraman</u> Shankar Venkataraman
4)	_____	, 2004	_____
5)	<u>5/28/04</u>	, 2004	<u>M. Ziaul Karim</u> M. Ziaul Karim
6)	<u>5/24/04</u>	, 2004	<u>Thanh N. Pham</u> Thanh N. Pham
			<u>Ellie Y. Yieh</u> Ellie Y. Yieh

60203992 v1

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Names and Addresses
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1)	Jeong Soo Byun 20975 Valley Green Drive, #257 Cupertino, CA 95014 United States	2)	Zheng Yuan 42024 Benbow Drive Fremont, CA 94539 United States
3)	Shankar Venkataraman 3444 Notre Dame Drive Santa Clara, CA 95051 United States	4)	M. Ziaul Karim 2820 McAnn Court San Jose, CA 95121 United States
5)	Thanh N. Pham 3794 Meadowlands Lane San Jose, CA 95135 United States	6)	Ellie Y. Yieh 5888 Pistola Way San Jose, CA 95138 United States

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NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

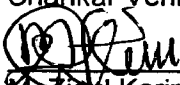
1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

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1) _____, 2004	_____
	Jeong Soo Byun
2) _____, 2004	_____
	Zheng Yuan
3) _____, 2004	_____
	Shankar Venkataraman
4) <u>May 24, 2004</u> , 2004	
	M. Ziaul Karim
5) _____, 2004	_____
	Thanh N. Pham
6) _____, 2004	_____
	Ellie Y. Yieh

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